



MACMIC

March 2011

PRELIMINARY

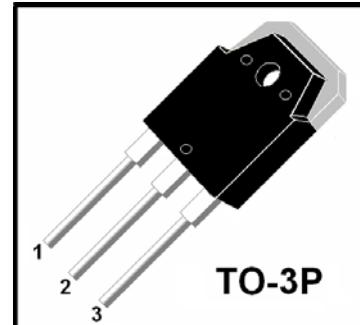
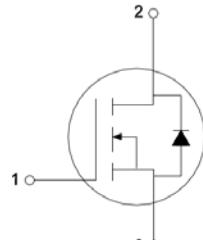
MM15N050P

500V 15A N-Channel MOSFET

RoHS Compliant

FEATURES

- Low drain-source ON resistance
- High forward transfer admittance
- Repetitive avalanche ratings
- Simple drive requirements
- Ease of paralleling



APPLICATIONS

- Switching power supplies
- Motor controls
- Inverters and choppers
- Audio amplifiers and energy pulse circuits

1.GATE
2.DRAIN
3.SOURCE

ABSOLUTE MAXIMUM RATINGS

$T_c=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Conditions	Values	Unit
V_{DSS}	Drain - Source Voltage	$T_j=25^\circ\text{C}$	500	V
V_{GSS}	Gate - Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_c=25^\circ\text{C}$	22	A
		$T_c=100^\circ\text{C}$	15	A
I_{DM}	Pulsed Drain Current	Limited by T_{jmax}	60	A
P_D	Maximum Power Dissipation		150	W
E_{AS}	Single Pulse Avalanche Energy		800	mJ
I_{AR}	Avalanche Current		22	A
E_{AR}	Repetitive Avalanche Energy		25	mJ
T_J	Operating Junction		150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range		-55~150	$^\circ\text{C}$
Weight			12	g

THERMAL CHARACTERISTICS

$T_c=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Conditions	Values	Unit
$R_{th(ch-c)}$	Thermal resistance,channel to case		0.83	$^\circ\text{C}/\text{W}$
$R_{th(ch-a)}$	Thermal resistance,channel to ambient		40	$^\circ\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS*T_C=25°C unless otherwise specified*

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	500			V	
R _{DS(ON)}	Drain-Source ON Resistance	V _{GS} =10V, I _D =7A		0.27		Ω	
		V _{GS} =10V, I _D =15A		0.28		Ω	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} = V _{DS} , I _D =250μA	2	3	4	V	
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±20V	-200		200	nA	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =500V, V _{GS} =0V			100	μA	
Q _g	Total Gate Charge	V _{DD} =300V, I _D =15A, V _{GS} =10V		99		nC	
Q _{gs}	Gate-Source Charge			35		nC	
Q _{gd}	Gate-Drain Charge			32		nC	
g _{fs}	Forward Transconductance	V _{DS} =50V, I _D =7A		12		S	
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f =1MHz		4400		pF	
C _{oss}	Output Capacitance			900		pF	
C _{rss}	Reverse Transfer Capacitance			270		pF	
t _{d(on)}	Turn - on Delay Time	V _{DD} =300V, I _D =15A, R _G =7.5 Ω, V _{GS} =10V, R _L =20 Ω	T _j =25°C	30		ns	
t _r	Rise Time		T _j =125°C	32		ns	
t _{d(off)}	Turn - off Delay Time		T _j =25°C	35		ns	
			T _j =125°C	38		ns	
t _f	Fall Time		T _j =25°C	100		ns	
			T _j =125°C	105		ns	
			T _j =25°C	28		ns	
			T _j =125°C	35		ns	

Source-Drain RATINGS AND CHARACTERISTICS*T_C=25°C unless otherwise specified*

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I _{SD}	Continuous Source-Drain Current				15	A
I _{SDM}	Pulse Source-Drain Current				60	A
V _{SD}	Source-Drain Voltage	I _{SD} =15A, V _{GS} =0V, T _j =25°C		0.85	1.6	V
t _{rr}	Reverse Recovery Time	I _{SD} =15A, di _{SD} /dt=-100A/μs T _j =25°C		420		ns
I _{RRM}	Max. Reverse Recovery Current			18		A
Q _{RRM}	Max. Reverse Recovery Charge			4.3		μC

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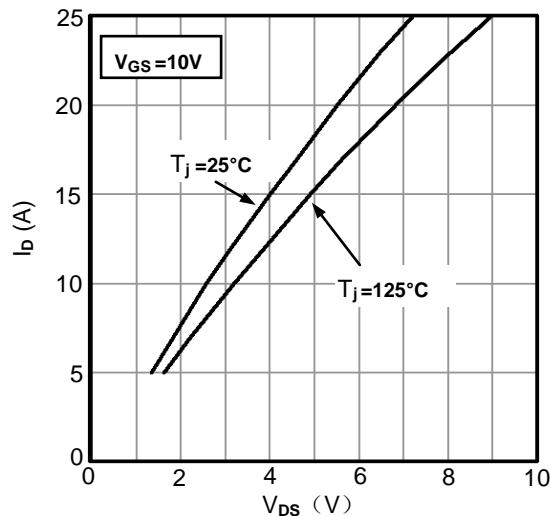


Figure 1. Typical Output Characteristics

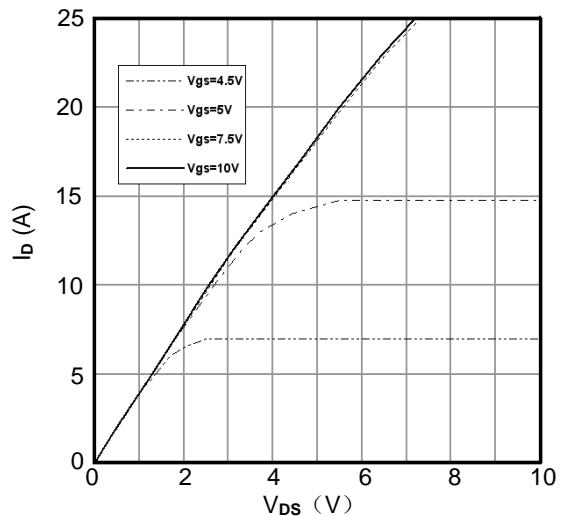


Figure 2. Typical Output Characteristics

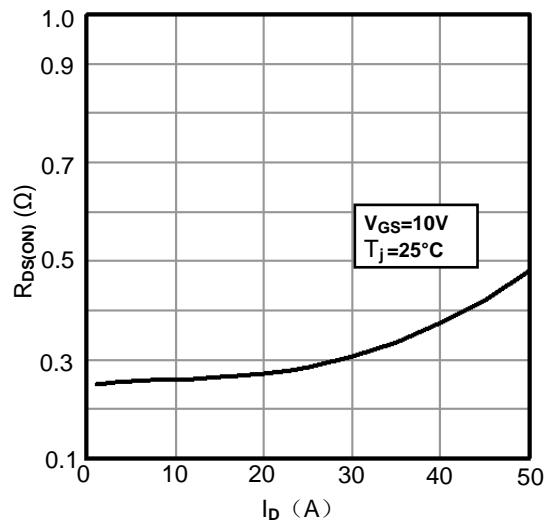


Figure 3. Drain-Source ON Resistance vs. I_D

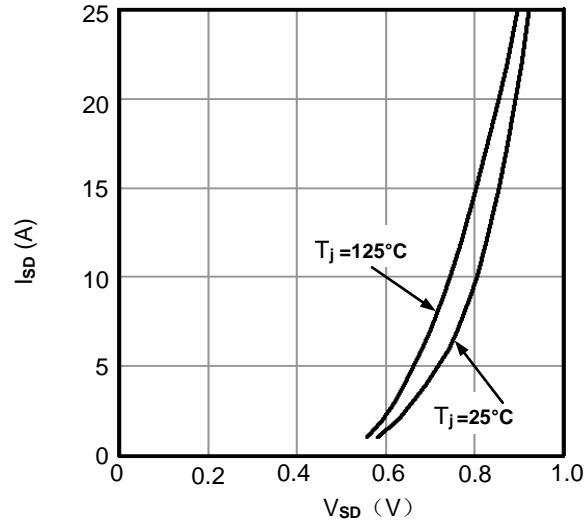


Figure 4. Source-Drain Voltage

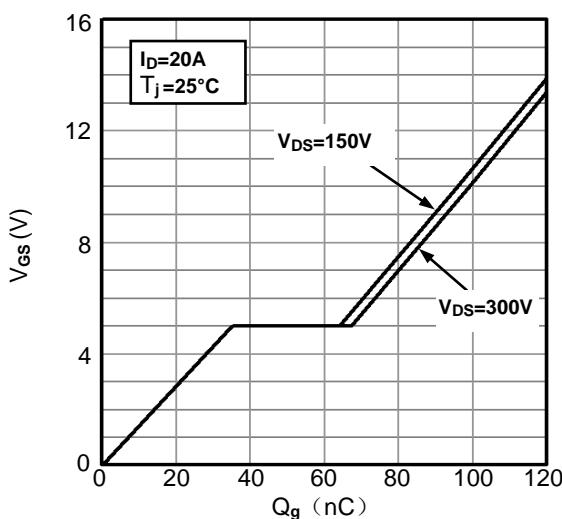


Figure 5. Gate Charge characteristics

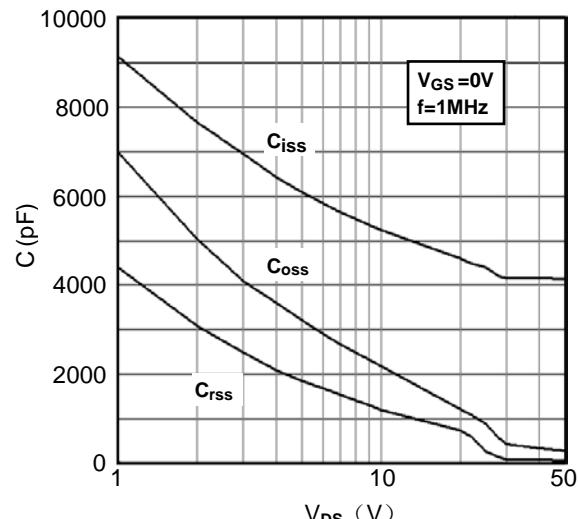


Figure 6. Typical Capacitances vs. V_{DS}

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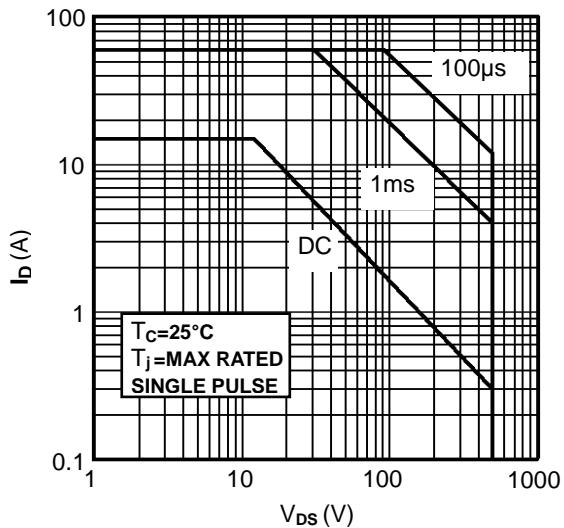


Figure 7. Forward Bias Safe Operating Area

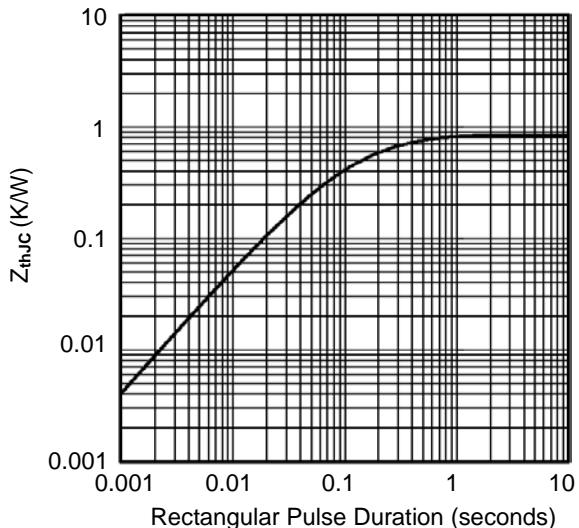


Figure 8. Transient Thermal Impedance

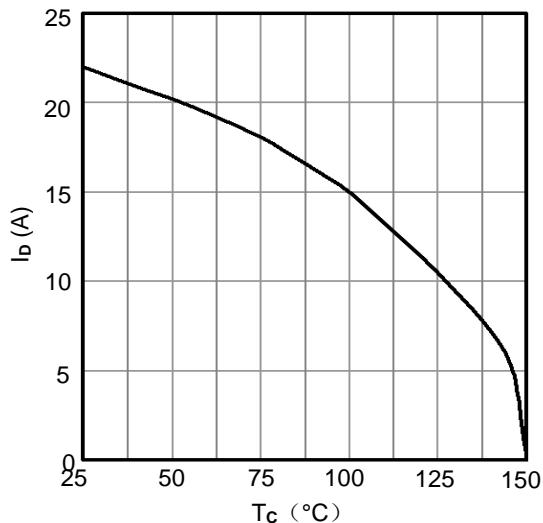


Figure 9. Maximum Continuous Drain Current vs. Case Temperature

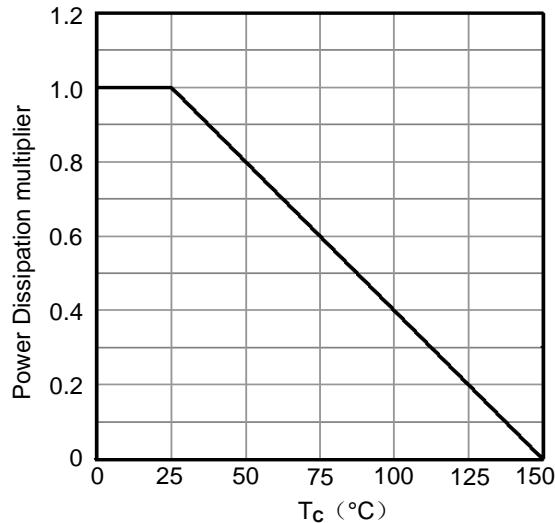


Figure 10. Normalized Power Dissipation vs. Case Temperature

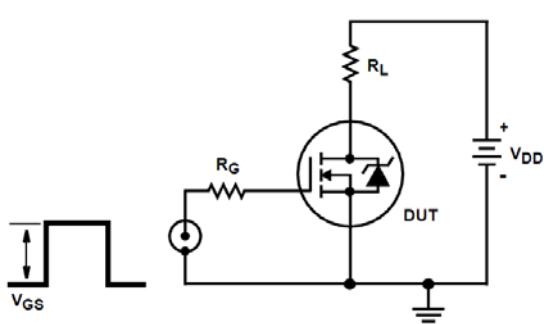


Figure 11. Switching Time Test Circuit

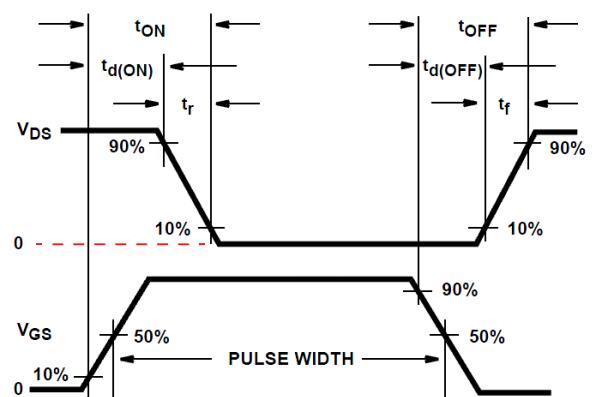


Figure 12. Resistive Switching Waveforms

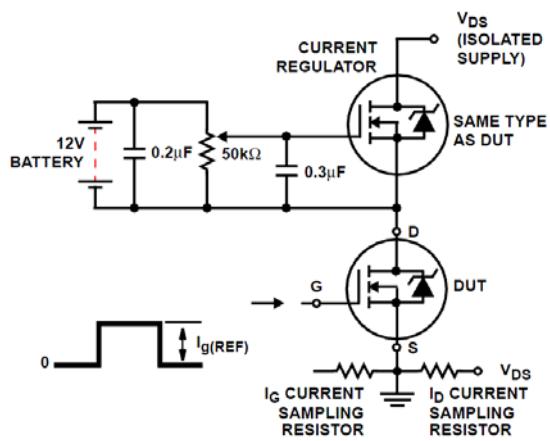


Figure13. Gate Charge Test Circuit

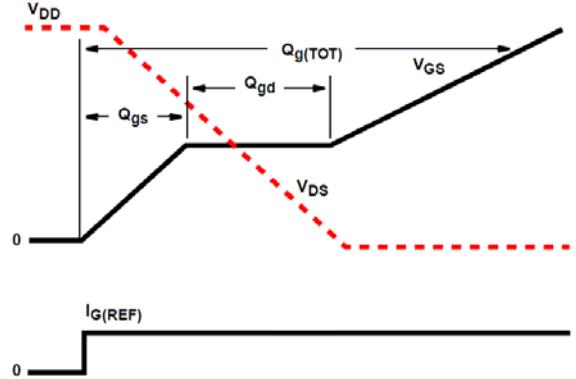
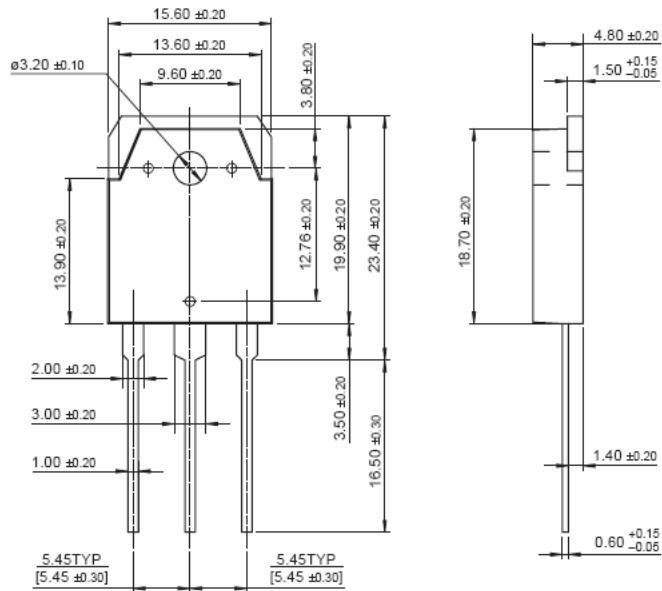


Figure14. Gate Charge Waveforms



Dimensions (mm)
Figure15. Package Outline